

Technical Data – HB060TC

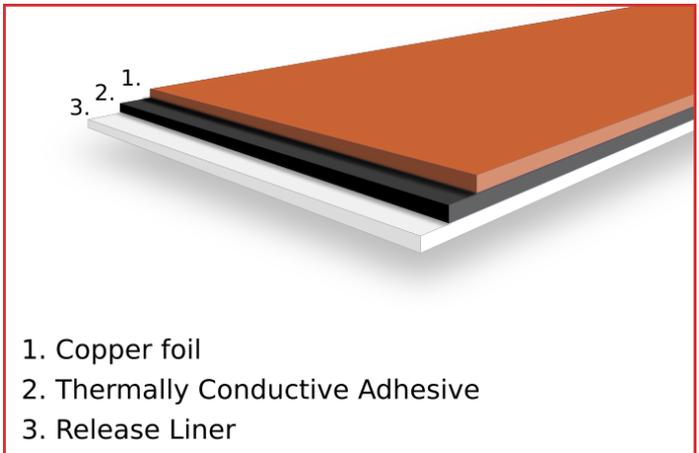
Product description

- Thermal Diffusivity Tape
- High Interface Performance
- Thin / Low Cost / Easy Design

Construction

- Copper: Fast heat spread
- Adhesive: With graphite adhesive
- Liner: Easy release liner

Technical data



1. Copper foil
2. Thermally Conductive Adhesive
3. Release Liner

Item	Unit	Spec.	Remarks
Total thickness	µm	60 (-5, +10)	Thickness Gauge
Adhesive strength	gf / inch	> 800	180° Peel / PET 25µm / SUS 304
Contact resistance – TOP	Ω / inch	Conductivity	1 inch surface resistance
Contact resistance – BOTTOM	Ω / inch	< 10 ⁶ Ω	1 inch surface resistance
Thermal conductivity (X-Y axis)	W/m.K	320	Copper's Property
Thermal conductivity (X-Y axis)	W/m.K	227 ↑	NETZSCH LFA (Aju Univ.)
Under the same conditions (LFA) measured. Film – coated graphite & HB060TC has similar performance 100~200W/m.K			
Operating Temperature	°C	-10 ~ 90	-

Application:

1. Mobile phone: Dual Core CPU / Firm / Battery (Cover)
2. LED TV, Notebook, Tablet PC and thin Electronics devices with High Efficiency
3. Heat Spreader for variety of applications
4. Currently in the approval for Mobile phone and Video equipments

Unless stated otherwise all values given are average. All of the tapes in our range should be thoroughly tested on the substrates in the particular application they are intended for. Hi-Bond Tapes Ltd. will not be responsible for product failure unless full testing has been completed. The customer has to decide on the tapes suitability for the intended application.